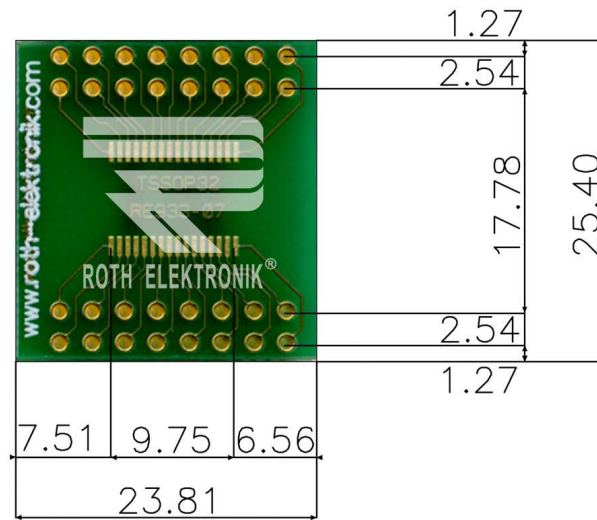


RE933-07

- Epoxy fibre-glass FR4 1.50 mm
 - Double-sided 35 µm Cu
 - Plated through holes (PTH)
 - Surface chem. Ni/Au with solder stop mask
 - Adaption circuit board for TSSOP 32
 - Pitch: 0.65 mm (240 mil)
 - Hole diameter 1.00 mm
 - Size 23.81 x 25.40 mm
- Module-No. Pitch mil Pin Size (mm)

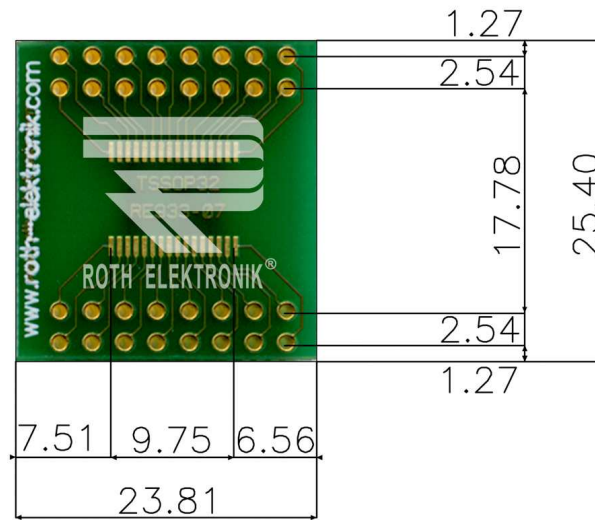
RE933-07 0.650 mm 22.5 32 4.400 (173 mil)



RE933-07

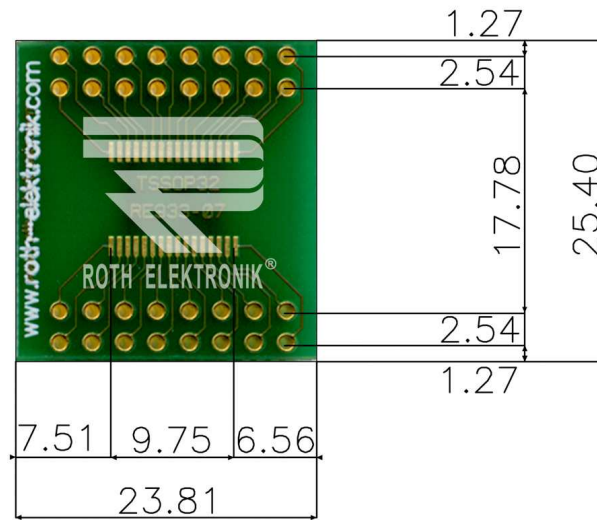
- Epoxydglashartgewebe FR4 1,50 mm
 - Zweiseitig 35 µm Cu
 - Durchkontaktiert (PTH)
 - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
 - Adaptionsplatine für TSSOP 32
 - Pitch: 0,65 mm (240 mil)
 - Lochdurchmesser 1,00 mm
 - Größe 23,81 x 25,40 mm
- Modul-Nr. Pitch mil Pin Größe (mm)

RE933-07 0,650 mm 22,5 32 4,400 (173 mil)



RE933-07

- Fibre de verre époxyde FR4 1,50 mm
 - Double face 35 µm Cu
 - Métallisation des trous (PTH)
 - Surface avec Ni/Au chimique et un laque d'arrêt de soudure
 - Platine d'adaptation pour TSSOP 32
 - Pitch: 0,65 mm (240 mil)
 - Perforation 1,00 mm Ø
 - Dimensions 23,81 x 25,40 mm
- Module-No. Pitch mil Pin Dimensions (mm)
RE933-07 0.650 mm 22.5 32 4.400 (173 mil)



RE933-07

- Fibra de vidrio epoxídica FR4 1,50 mm
 - Por dos lados 35 µm de Cu
 - Agujeros con contactos metalizados (PTH)
 - Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
 - Adaptador para TSSOP 32
 - Pitch: 0,65 mm (240 mil)
 - Agujeros Ø 1,00 mm
 - Tamaño 23,81 x 25,40 mm
- Módulo-No. Pitch mil Pin Tamaño (mm)

RE933-07 0.650 mm 22.5 32 4.400 (173 mil)